

# **Product End-of-Life Disassembly Instructions**

Product Category: Personal Computers	
Marketing Name / Model [List multiple models if applicable.]	
Compaq Presario CQ1 All-In-One PC	

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

#### **1.0 Items Requiring Selective Treatment**

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	10
Batteries	All types including standard alkaline and lithium coin or button style batteries	9
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	4
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink,	Include the cartridges, print heads, tubes, vent	0

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including liquids, semi-liquids (gel/paste) and toner	chambers, and service stations.	
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

#### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1	
Description #2	
Description #3	
Description #4	
Description #5	
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#### **3.0 Product Disassembly Process**

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- 1.
- 2.
- 3.
- 4. 5.
- 6.
- 7.
- 8.

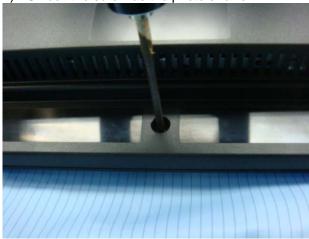
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 : Mechanical parts disassembly

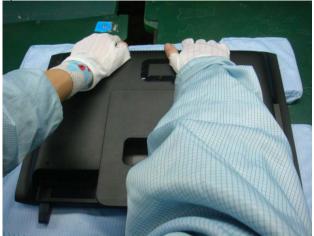
1) Put the unit on a platform and let the stand upside.



2) Unlock the screw as the photo shows



3) Disassemble the rear cover of the machine



EL-MF877-00 Template Revision B 4) Unlock the 2 screws on the iron.



5) Unlock the screw of the cover.



6) Disassemble the foot as photo show.



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#### 7) Disassemble the speaker



8) Disassemble the base pan and front bezel

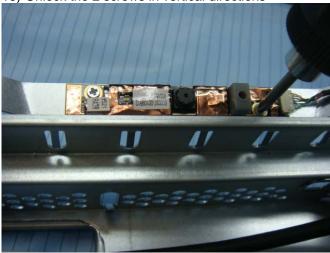






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10) Unlock the 2 screws in vertical directions



11) Unlock the 3 screws and take the H/S out.



12) Pull the cable out.

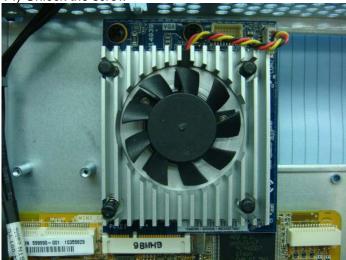


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## 13) Disassemble the inverter board



14) Unlock the screw

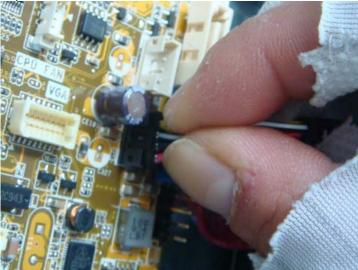


15) Disassemble the WL module



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16) Pull the HDD cable and inverter cable out



17) Disassemble it on basepan



18) Take the DDR cover off



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# 19) Take the ODD off from the unit



20) Take the MB off from the unit



21) Tear antenna off



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## 22) Tear side IO label off from the base pan





Figure 2: CCFLs Remove from Panel

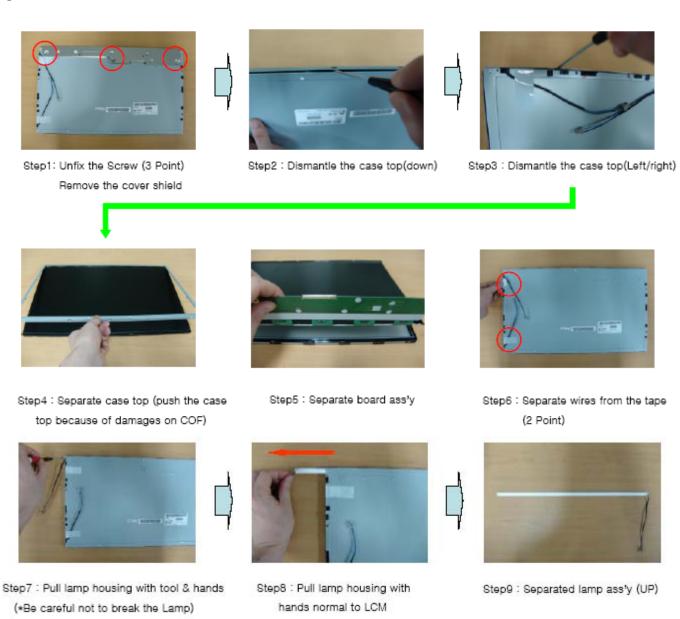
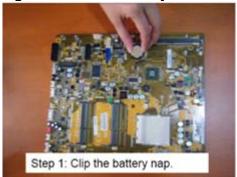


Figure 3 : Remove Battery from MB.





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